L	Hits	Search Text	DB	Time stamp
Number	0.550.455			10004/05/05
1	2552477	semiconductor chip die flipchip (flip adj	USPAT;	2004/07/27
		chip) ic (integrated adj circuit)	US-PGPUB;	19:44
	1		EPO; JPO;	
	1		DERWENT;	
			IBM_TDB	
2	8128983	lwith (through hope via)	USPAT;	2004/07/27
			US-PGPUB;	19:43
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
3	428874	(semiconductor chip die flipchip (flip	USPAT;	2004/07/27
		adj chip) ic (integrated adj circuit))	US-PGPUB;	19:44
		with (through hope via)	EPO; JPO;	1
		with (diffought hope via)	DERWENT;	
			IBM TDB	
4	159597	(wiring) with (substrate board carrier)	USPAT;	2004/07/27
	139391	(willing) with (substrate board carrier)	US-PGPUB;	19:44
			EPO; JPO;	13.44
			DERWENT;	
	14060	Manufacture Acceptance with the City of the Manufacture (City of the City of t	IBM_TDB	2004/07/07
5	14968	((semiconductor chip die flipchip (flip	USPAT;	2004/07/27
		adj chip) ic (integrated adj circuit))	US-PGPUB;	19:44
		with (through hope via)) same ((wiring)	EPO; JPO;	
		with (substrate board carrier))	DERWENT;	
			IBM_TDB	
6	703		USPAT;	2004/07/27
		(((semiconductor chip die flipchip (flip	US-PGPUB;	19:46
		adj chip) ic (integrated adj circuit))	EPO; JPO;	
		with (through hope via)) same ((wiring)	DERWENT;	
		with (substrate board carrier)))	IBM_TDB	
7	417	((flipchip (flip adj chip)) same	USPAT;	2004/07/27
		(((semiconductor chip die flipchip (flip	US-PGPUB;	19:46
		adj chip) ic (integrated adj circuit))	EPO; JPO;	
		with (through hope via)) same ((wiring)	DERWENT;	
		with (substrate board carrier)))) and	IBM TDB	
	1	(package packaging packaged)		